



Substrate: 1.59mm ± 0.18 mm [0.0625" ± 0.007 "] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.



Pins: shell material- 0.0035 ± 0.0003 BeCu #172 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).

Description: Probe Board for TEKTRONIX TLA700 series Logic Analyzer

680 position BGA land socket to 680 position surface mountable BGA emulator foot, with latch housing high density Mictor connectors on the Probe Board. Pin assignment/ interconnect is configured for the XILINX FG680 IC and Tektronix TLA 700 series logic analyzer.

Tolerances: diameters ± 0.03 mm [± 0.001 "], PCB perimeters ± 0.13 mm [± 0.005 "], PCB thicknesses ± 0.18 mm [± 0.007 "], pitches (from true position) ± 0.08 mm [± 0.003 "], all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

PB-BGA-FG680-01 Drawing

Status: Released

Scale: 2:1

Rev: C



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